upplier Information  ompany name*	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name*   Company unique ID   Unique ID Authority   Response Date*   2025-07-03   2025-0	752-21.1											ials and Mi	g Informati	ion	
Semilar   Semi	upplier Informa	ition													
Title - Contact Name  Product Enviso Compliance  Product Enviso Compliance  NA  Product Enviso Consemi.com  Na Unit Title - Representative *  Na Nanufacturing Site  Nanufacturing Site  Nanufacturing Site  Na Nanufacturing Si	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product Env-Stewards uthorized Representative* Title - Representative Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards NA Product-Env-Stewards NA Product-Env-Stewards NA Product-Env-Stewards NA Product-Env-Stewards NA Nanufacturing Site Weight* UOM Unit Ty In the Name Nanufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy  1 260 C 30 seconds  Terminal Plating soldering is 10-30 seconds	nsemi											2025-07-03			
Title - Representative* Product-Env-Stewards Product Enviro Compliance NA Requester Item Number Mfr Item Numbe	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit Ty  CN1 1.734 mg Each  Manufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed CU Alloy 1 Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM Unit Ty  CN1 1.734 mg Each  Max Time at Peak Temperature Number of Reflow Cycles Seconds  Output  Description of Reflow Cycles Seconds  Matter Tin (Sn) - annealed CU Alloy Matter Tin (Sn) - annealed CU Alloy Matter Tin (Sn) - annealed Max Time at Peak Temperature Number of Reflow Cycles Matter Tin (Sn) - annealed Max Time at Peak Temperature Number of Reflow Cycles Max Time Alloy Max T	Product-Env-Steware	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represent	tative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
BAT54XV2T1G   SCHOTTKY DIODE SOD523   2025-07-03   CN1   1.734   mg   Each	Product-Env-Steward	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cycles	Requester	Requester Item Number Mfr It		Item Number Mfr Item Name				Effective Date	e Version	n I	Manufacturing Site		Veight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  CU Alloy  1 260  Seconds  Terminal Plating / Grid Array Material  Number of Reflow Cycles  260  Seconds  Terminal Plating / Grid Array Material  Number of Reflow Cycles  260  Seconds			BAT54X	V2T1G	SCHOTTKY DIOD	DE SOD523		2025-07-03		-	CN1	1	.734	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3  omments vel 1 - maximum time at peak temperature during soldering is 10-30 seconds				amain al Daga	Allow	CTD 020 MCI	Dating	Dools Duo	anna Dadu	Tomanoustu	May Time at Peak	Tommonoto	uno Niversite	an of Deflow Cv	alac
omments vel 1 - maximum time at peak temperature during soldering is 10-30 seconds				,		S1D-020 MSL	_ Rating							ber of Reflow Cyc	cies
vel 1 - maximum time at peak temperature during soldering is 10-30 seconds	•	(Sn) - annealed	C	U Alloy	I			200		JC	30	second	18 3		
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or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	led					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the					
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.04	mg	Supplier	Silicon (Si)	7440-21-3		0.04	mg
Lead Frame	0.58		В	Nickel (Ni)	7440-02-0		0.221	mg
			Supplier	Iron (Fe)	7439-89-6		0.3051	mg
			Supplier	Copper (Cu)	7440-50-8		0.0539	mg
Mold Compound-Black	1.08		Supplier	Boron zinc hydroxide oxide	138265-88-0		0.0324	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		0.0054	mg
			Supplier	2,4,6-triamino-s-triazincompd.withs-triazine-triol	37640-57-6		0.0324	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.864	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0108	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.0864	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0486	mg
Plating	0.03	mg	Supplier	Tin (Sn)	7440-31-5		0.03	mg
Wire Bond - Cu	0.004	mg	Supplier	Copper (Cu)	7440-50-8		0.004	mg